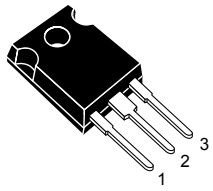
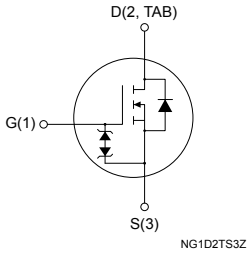
N-channel 950 V, 110 mΩ typ., 38 A MDmesh K5 Power MOSFET in a TO-247 package



TO-247



Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STW40N95K5	950 V	130 mΩ	38 A

- Ultra-low gate charge
- Very low FoM (figure of merit)
- Zener-protected
- 100% avalanche tested

Applications

- Switching applications

Description

This very high voltage N-channel Power MOSFET is designed using MDmesh K5 technology based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance and ultra-low gate charge for applications requiring superior power density and high efficiency.

Product status link
STW40N95K5

Product summary	
Order code	STW40N95K5
Marking	40N95K5
Package	TO-247
Packing	Tube

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	±30	V
I_D	Drain current (continuous) at T_C = 25 °C	38	A
	Drain current (continuous) at T_C = 100 °C	24	
I_{DM}(1)	Drain current (pulsed)	152	A
P_{TOT}	Total power dissipation at T_C = 25 °C	450	W
dv/dt(2)	Peak diode recovery voltage slope	4.5	V/ns
dv/dt(3)	MOSFET dv/dt ruggedness	50	V/ns
T_{stg}	Storage temperature range	-55 to 150	°C
T_J	Operating junction temperature range		°C

1. *Pulse width limited by safe operating area.*
2. *I_{SD} ≤ 19 A, V_{DS} (peak) < $V_{(BR)DSS}$, di/dt = 100 A/µs.*
3. *V_{DD} = 760 V.*

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance, junction-to-case	0.28	°C/W
R_{thJA}	Thermal resistance, junction-to-ambient	50	°C/W

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_J max.)	13	A
E_{AS}	Single pulse avalanche energy (starting T_J = 25 °C, I_D = I_{AR}, V_{DD} = 50 V)	700	mJ

2 Electrical characteristics

T_C = 25 °C unless otherwise specified.

Table 4. On/off-states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 1 mA	950			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 950 V			1	µA
		V_{GS} = 0 V, V_{DS} = 950 V, T_C = 125 °C (1)			50	
I_{GSS}	Gate-body leakage current	V_{DS} = 0 V, V_{GS} = ±20 V			±10	µA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 100 µA	3	4	5	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 19 A		110	130	mΩ

1. *Specified by design, not tested in production.*

Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 100 V, f = 1 kHz, V_{GS} = 0 V	-	3300	-	pF
C_{oss}	Output capacitance		-	250	-	pF
C_{rss}	Reverse transfer capacitance		-	2	-	pF
$C_{o(tr)}$ (1)	Equivalent capacitance, time-related	V_{DS} = 0 to 760 V, V_{GS} = 0 V	-	398	-	pF
$C_{o(er)}$ (2)	Equivalent capacitance, energy-related		-	142	-	pF
R_g	Intrinsic gate resistance	f = 1 MHz, I_D = 0 A	-	5	-	Ω
Q_g	Total gate charge	V_{DD} = 760 V, I_D = 38 A, V_{GS} = 0 to 10 V (see Figure 15. Test circuit for gate charge behavior)	-	93	-	nC
Q_{gs}	Gate-source charge		-	18.7	-	nC
Q_{gd}	Gate-drain charge		-	63.4	-	nC

1. *$C_{o(tr)}$ is a constant capacitance value that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}.*
2. *$C_{o(er)}$ is a constant capacitance value that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}.*

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 475 V, I_D = 19 A, R_G = 4.7 Ω , V_{GS} = 10 V (see Figure 14. Test circuit for resistive load switching times and Figure 19. Switching time waveform)	-	33.5	-	ns
t_r	Rise time		-	51	-	ns
$t_{d(off)}$	Turn-off delay time		-	91.5	-	ns
t_f	Fall time		-	10	-	ns

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		38	A
I_{SDM}(1)	Source-drain current (pulsed)		-		152	A
V_{SD}(2)	Forward on voltage	V_{GS} = 0 V, I_{SD} = 38 A	-		1.5	V
t_{rr}	Reverse recovery time	I_{SD} = 38 A, di/dt = 100 A/µs, V_{DD} = 60 V (see Figure 16. Test circuit for inductive load switching and diode recovery times)	-	706		ns
Q_{rr}	Reverse recovery charge		-	22		µC
I_{RRM}	Reverse recovery current		-	62		A
t_{rr}	Reverse recovery time	I_{SD} = 38 A, di/dt = 100 A/µs, V_{DD} = 60 V, T_J = 150 °C (see Figure 16. Test circuit for inductive load switching and diode recovery times)	-	886		ns
Q_{rr}	Reverse recovery charge		-	28.2		µC
I_{RRM}	Reverse recovery current		-	64		A

1. *Pulse width is limited by safe operating area.*
2. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%.*

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

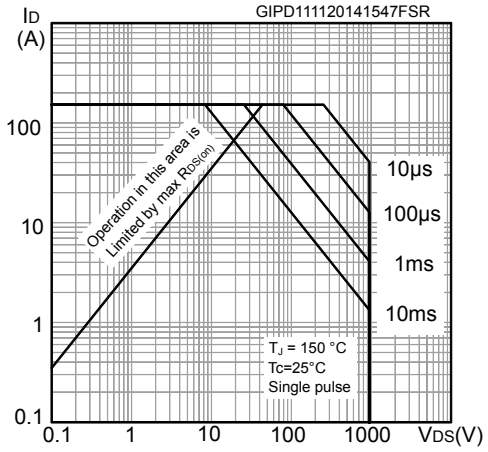


Figure 2. Normalized transient thermal impedance

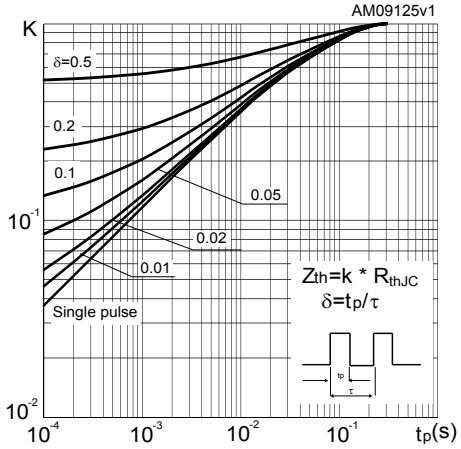


Figure 3. Typical output characteristics

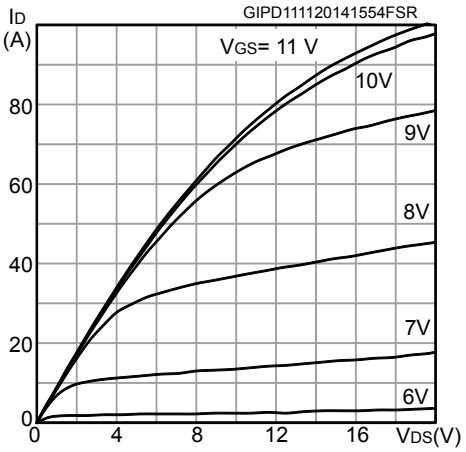


Figure 4. Typical transfer characteristics

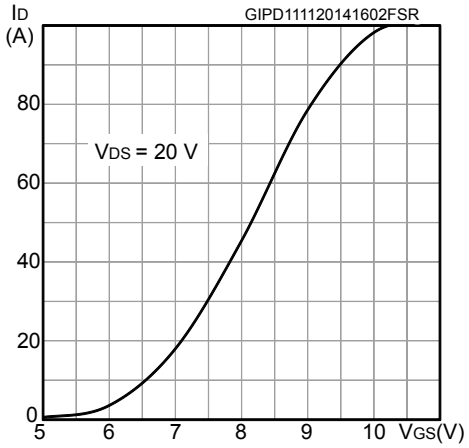


Figure 5. Typical gate charge characteristics

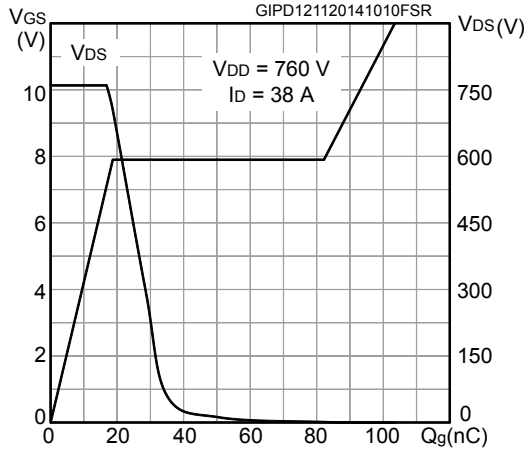


Figure 6. Typical drain-source on-resistance

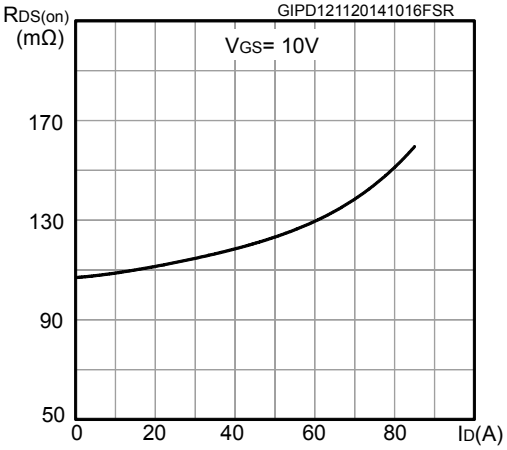


Figure 7. Typical capacitance characteristics

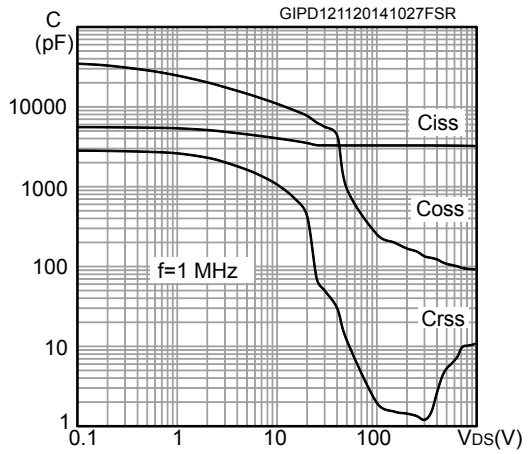


Figure 8. Normalized gate threshold vs temperature

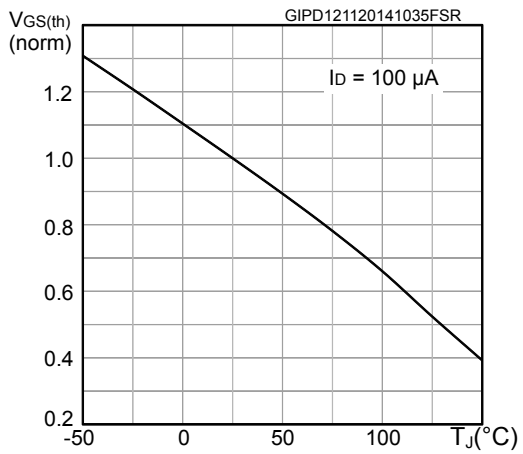


Figure 9. Normalized on-resistance vs temperature

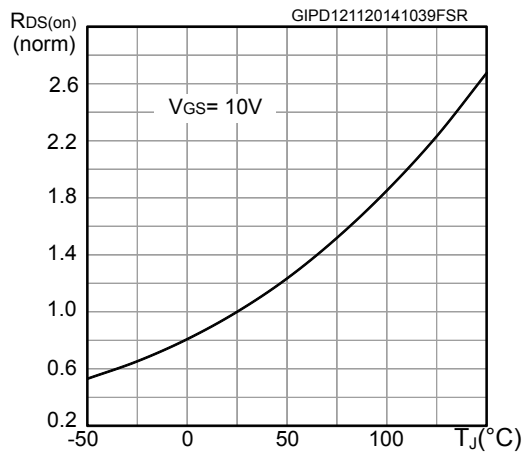


Figure 10. Normalized breakdown voltage vs temperature

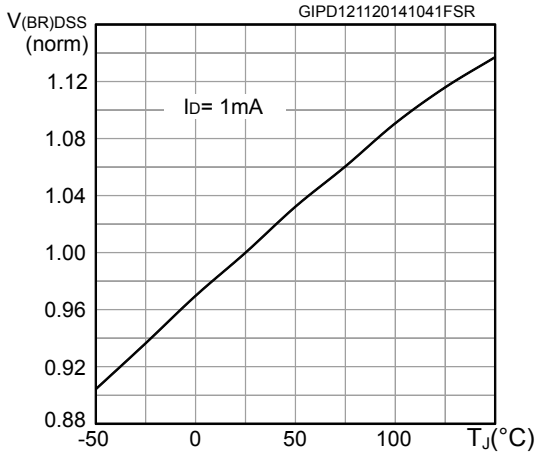


Figure 11. Typical output capacitance stored energy

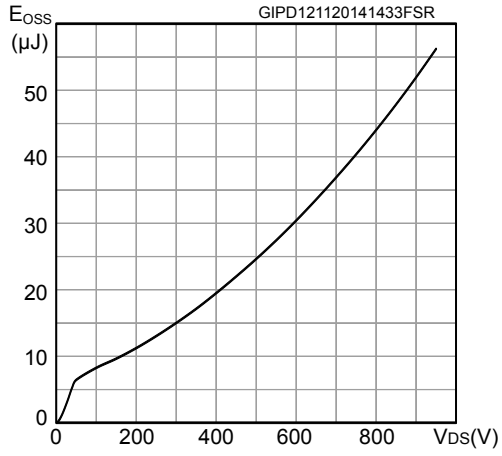


Figure 12. Typical reverse diode forward characteristics

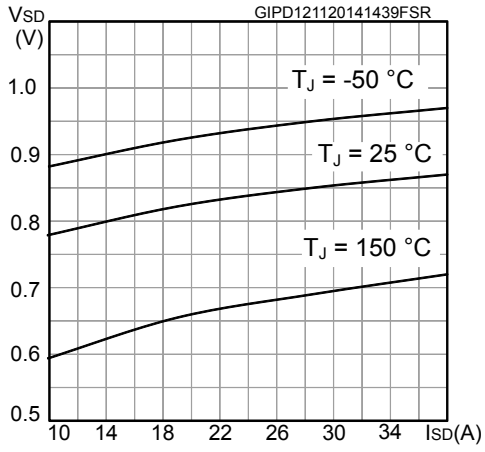
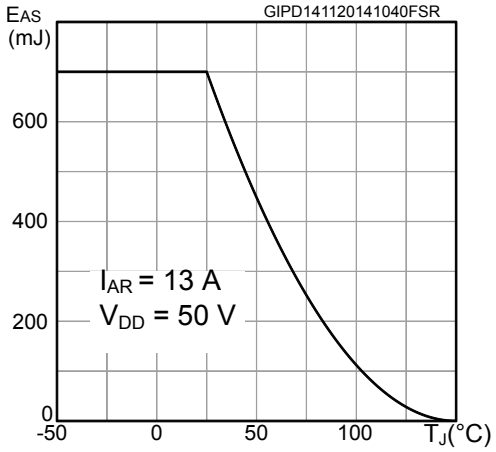
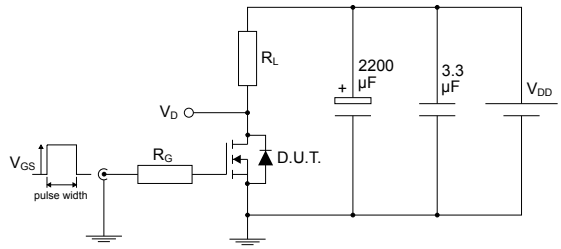


Figure 13. Maximum avalanche energy vs temperature



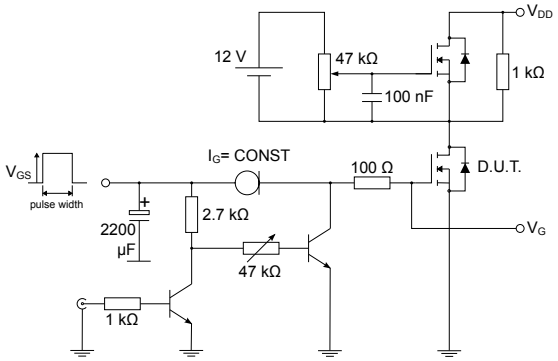
3 Test circuits

Figure 14. Test circuit for resistive load switching times



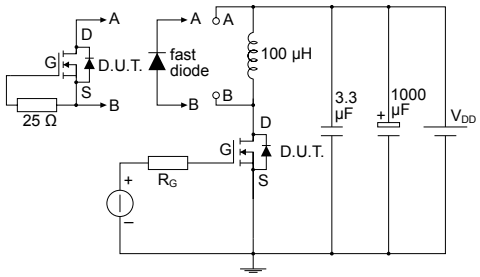
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Figure 15. Test circuit for gate charge behavior



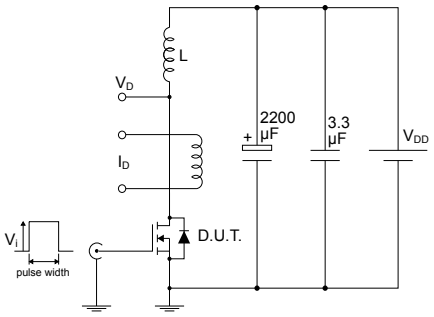
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Figure 16. Test circuit for inductive load switching and diode recovery times



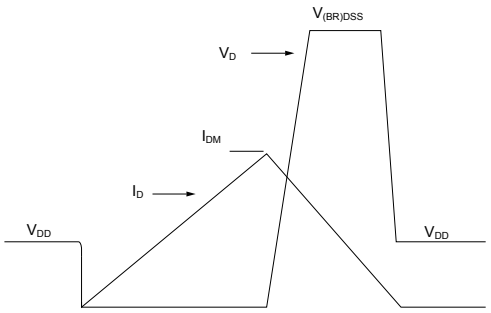
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Figure 17. Unclamped inductive load test circuit



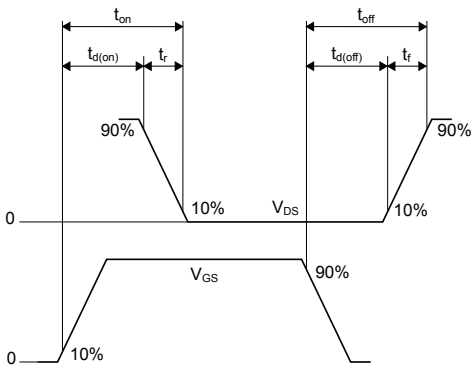
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Figure 18. Unclamped inductive waveform



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Figure 19. Switching time waveform



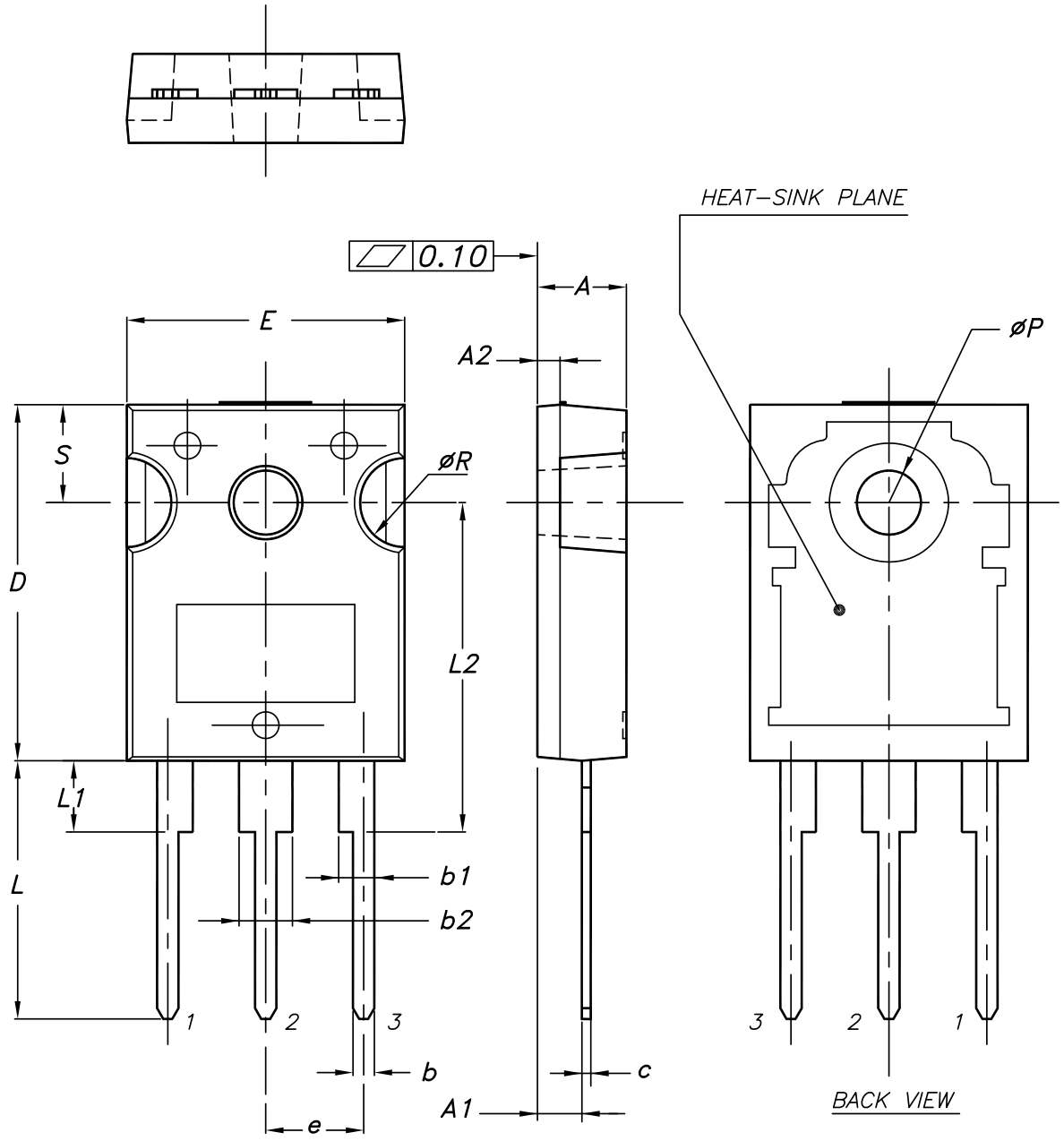
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4 Package information

To meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 TO-247 package information

Figure 20. TO-247 package outline



0075325_11

Table 8. **TO-247 package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
A2		1.27	
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

Revision history

Table 9. **Document revision history**

Date	Revision	Changes
03-Jun-2014	1	First release.
14-Nov-2014	2	Document status promoted from preliminary to production data. Added *Section 2.1: "Electrical characteristics (curves)"*.
09-Apr-2026	3	Updated Section 4.1: TO-247 package information. Minor text changes.

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